



Serial I²C & SPI EEPROM in DFN8 package





Target applications DFN8 package

Drones



Headsets



Industrial IoT



Electronic shelf label



Designed for applications where **space and weight constraints** and **manufacturing robustness** are key factors





DFN8 package features

UFDFPN8 – MLP8

**DFN8 package: small, robust,
easy to handle**



**UFDFPN: Ultra-thin
Fine-pitch Dual Flat
Package No lead**

Features	DFN8
Package size	2 x 3 mm
Thickness	0.55 mm
Weight	16 mg
Pin count	8 pin
Pin type	Leadless
Solder pitch	0.5 mm

Package information and soldering guidelines available in [TN1171](#)



I²C & SPI EEPROM DFN8 portfolio

UFDFPN8 – MLP8

The DFN8 package offers significant improvements

- reduced PCB footprint
- reduced application weight
- easy handling and manufacturing robustness



Notes:

1/ All products, except “-F” version that operates at 1.6 V, operate in the 1.7 to 5.5 V V_{CC} range and - 40 to + 85 °C temperature range
 2/ “-DRE » version are available in MLP8


 Click on product name to download the Datasheet Part numbers		Memory density (Kbits)	I ² C Commercial part numbers (CPNs)	SPI Commercial part numbers (CPNs)
I ² C	SPI			
M24C02-F & M24C02-DRE		2	M24C02-FMH6TG * M24C02-DRMF8TG/K	-
M24C04-F & M24C04-DRE	M95040-DF	4	M24C04-FMH6TG * M24C04-DRMF8TG/K	* M95040-DFMC6TG
M24C08-F & M24C08-DRE	M95080-DF	8	M24C08-FMH6TG * M24C08-DRMF8TG/K	* M95080-DFMC6TG
M24C16-F & M24C16-DRE	M95160-DF	16	M24C16-FMH6TG * M24C16-DRMF8TG/K	* M95160-DFMC6TG
M24C32-F & M24C32-DRE	M95320-DF	32	M24C32-FMH6TG * M24C32-DFMC6TG	* M95640-DFMC6TG
M24C64-F & M24C64-DRE	M95640-DF & M95640-DRE	64	M24C64-FMC6TG & *M24C64-DRMF8TG/K * M24C64-DFMC6TG	* M95640-DFMC6TG & *M95640-DRMF8TG/K
M24128-BF	M95128-DF	128	M24128-BFMC6TG * M24128-DFMC6TG	* M95128-DFMC6TG
M24256E-F	M95256-DF	256	* M24256E-FMC6TG	* M95256-DFMC6TG
M24512E-F	M95512-DF	512	* M24512E-FMC6TG	* M95512-DFMC6TG
M24M01E-F		1024	* M24M01E-FMC6TG	-
M24M02E-F		2048	* M24M02E-FMC6TG	-

Table legend: * Lockage ID page For new design





I²C & SPI EEPROM in DFN8 package summary

Designed for small & light modules where robustness is a key factor

- Wide I²C & SPI portfolio up to 2 Mbit
- Robust ROHS and leadless package
- Samples available now

- Request free samples or buy from [eStore](#)
- Prototype with [X-NUCLEO-EEPROMA2 shield](#)
- IBIS & soldering guidelines available on [st.com](#)

Our technology starts with You



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